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RClamp0521PA Ultra-Low Capacitance 1-Line ESD protection

RailClamp® TVS arrays are ultra low capacitance ESD protection devices designed to protect high speed data interfaces. This series has been specifically designed to protect sensitive components which are connected to high-speed data and transmission lines from overvoltage caused by ESD (electrostatic discharge), CDE (Cable Discharge Events), and EFT (electrical fast transients).

The RClamp®0521PA has a maximum capacitance of only 0.50pF. This allows it to be used on circuits operating in excess of 3GHz without signal attenuation. They may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 ($\pm 15\text{kV}$ air, $\pm 8\text{kV}$ contact discharge).

The RClamp0521PA is in a 2-pin SLP1006P2 package measuring 1.0 x 0.6 x 0.5mm. The leads are spaced at a pitch of 0.65mm and feature a lead-free finish. Each device will protect one high-speed line operating at 5 volts. It gives the designer the flexibility to protect single lines in applications where arrays are not practical. The combination of small size, low capacitance, and high ESD surge capability makes them ideal for use in applications such as cellular phones and digital video interfaces.

- ◆ Transient protection for data lines to
IEC 61000-4-2 (ESD) $\pm 15\text{kV}$ (air), $\pm 8\text{kV}$ (contact)
IEC 61000-4-4 (EFT) 40A (tp = 5/50ns)
Cable Discharge Event (CDE)
- ◆ Ultra-small package (1.0 x 0.6 x 0.5mm)
- ◆ Protects one data or I/O line
- ◆ Low capacitance: **0.5pF**
- ◆ Low clamping voltage
- ◆ Low operating voltage: 5.0V
- ◆ Solid-state silicon-avalanche technology

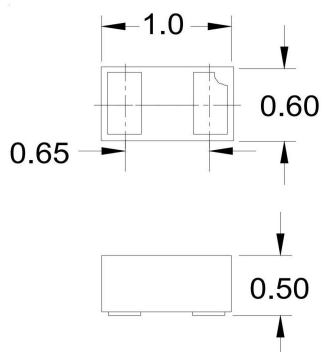
Mechanical Characteristics

- ◆ SLP1006P2 package
- ◆ Molding compound flammability rating: UL 94V-0
- ◆ Marking: Marking code
- ◆ Packaging: Tape and Reel
- ◆ Lead Finish: NiPdAu
- ◆ Pb-Free, Halogen Free, RoHS/WEEE Compliant

Applications

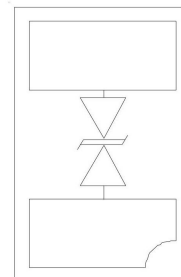
- ◆ Cellular Handsets & Accessories
- ◆ Digital Visual Interface (DVI)
- ◆ Display Port
- ◆ MDDI Ports
- ◆ USB Ports
- ◆ PCI Express
- ◆ Serial ATA

Dimensions



Maximum Dimensions (mm)

Schematic & PIN Configuration



SLP1006P2 (Bottom View)

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Absolute Maximum Rating

Rating	Symbol	Value	Units
Peak Pulse Power ($t_p = 8/20\mu s$)	P_{pk}	100	Watts
Peak Pulse Current ($t_p = 8/20\mu s$)	I_{pp}	4	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	+/- 15 +/- 8	kV
Operating Temperature	T_J	-55 to +125	°C
Storage Temperature	T_{STG}	-55 to +150	°C

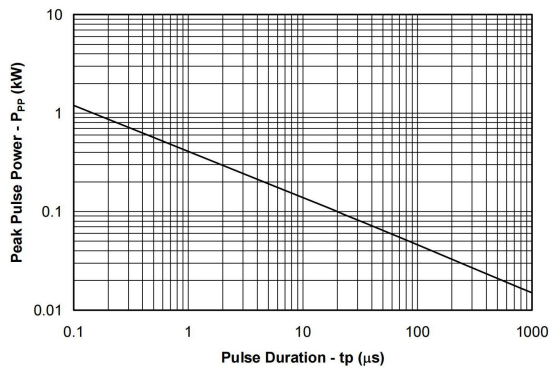
Electrical Characteristics (T=25°C)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V_{RWM}				5	V
Reverse Breakdown Voltage	V_{BR}	$I_t = 1mA$	6	9.3	11	V
Reverse Leakage Current	I_R	$V_{RWM} = 5V, T=25^\circ C$		0.025	1	μA
Clamping Voltage	V_C	$I_{pp} = 1A, t_p = 8/20\mu s$			15	V
Clamping Voltage	V_C	$I_{pp} = 4A, t_p = 8/20\mu s$			25	V
Junction Capacitance	C_J	$V_R = 0V, f = 1MHz$		0.30	0.50	pF

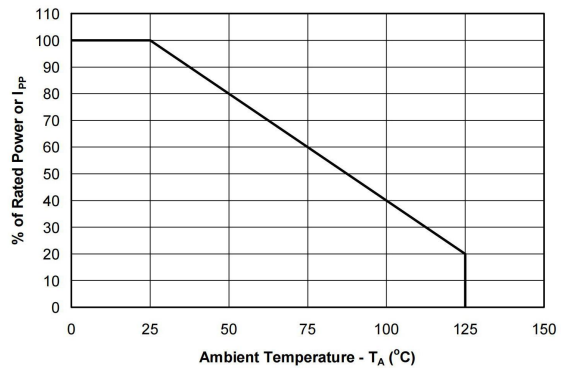
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Typical Characteristics

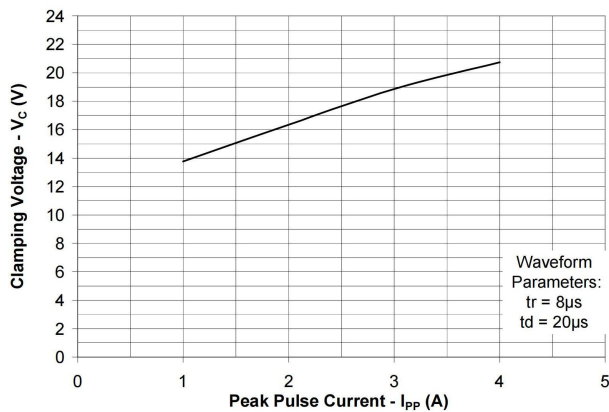
Non-Repetitive Peak Pulse Power vs. Pulse Time



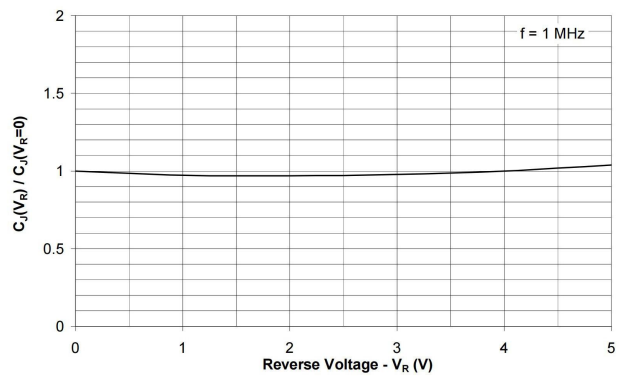
Power Derating Curve



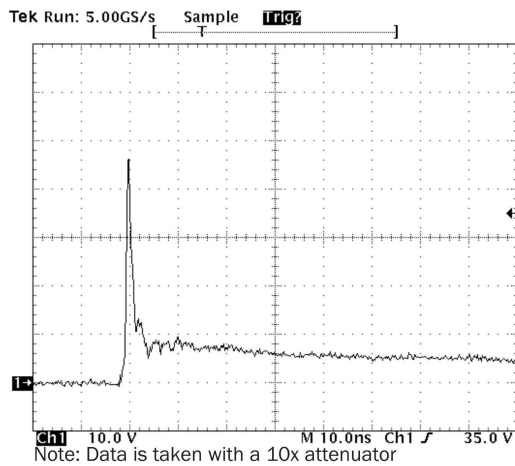
Clamping Voltage vs. Peak Pulse Current



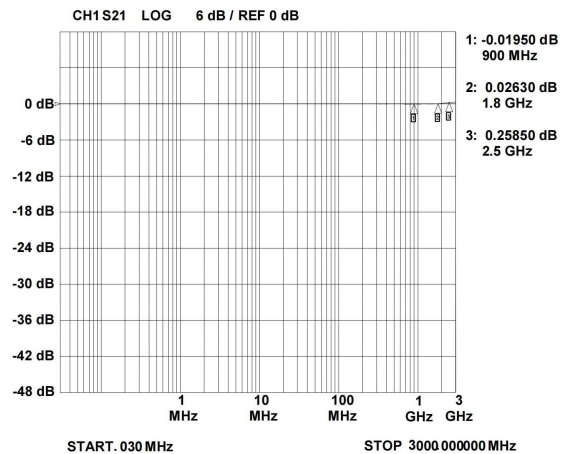
Normalized Capacitance vs. Reverse Voltage



**ESD Clamping
(8kV Contact per IEC 61000-4-2)**



Insertion Loss S21

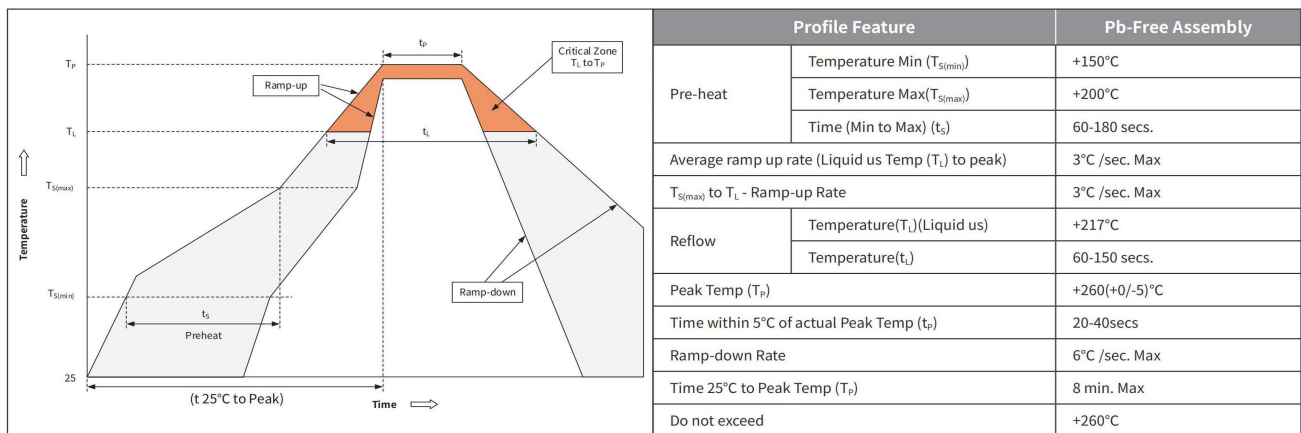


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Ordering Information

PREFERRED P/N	PACKAGE	SIZE(mm)	DELIVERY MODE	MPQ(PCS)
	DFN1006-2L	1.00×0.60×0.37	7" REEL	10,000

Recommended Soldering Conditions



Package Outline Dimensions (DFN1006-2L)

Symbol	Dimensions			
	Millimeters		Inches	
	Min	Max	Min	Max
A	0.950	1.050	0.037	0.041
B	0.550	0.650	0.022	0.026
C	0.350	0.450	0.014	0.018
D	0.550	0.650	0.022	0.026
D ₁	0.280	0.380	0.011	0.015
E	0.450	0.550	0.018	0.022
L	0.000	0.100	0.000	0.004

Suggested Pad Layout

Symbol	Dimensions			
	Millimeters		Inches	
	Min	Max	Min	Max
J	0.50	0.60	0.020	0.024
K	0.25	0.35	0.010	0.014
M	0.55	0.65	0.022	0.026